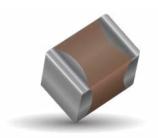
## **X7S Dielectric**

## **General Specifications**





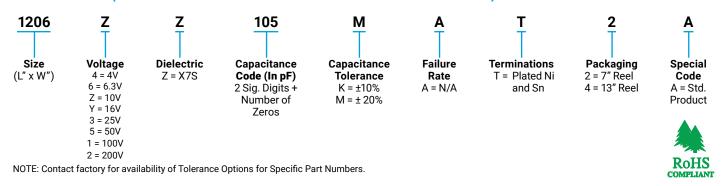
#### **GENERAL DESCRIPTION**

X7S formulations are called "temperature stable" ceramics and fall into EIA Class II materials. Its temperature variation of capacitances within ±22% from -55°C to +125°C. This capacitance change is non-linear.

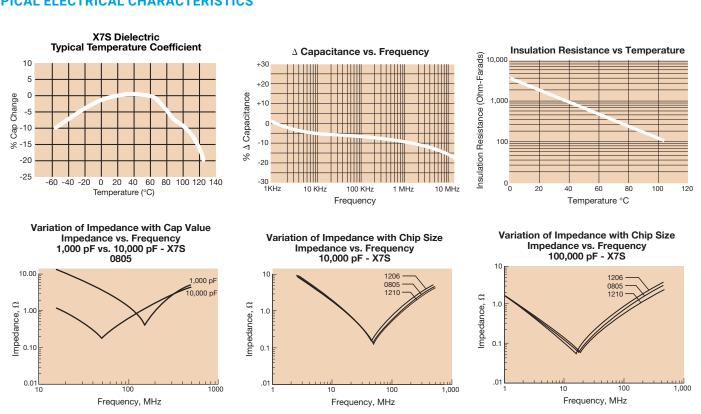
Capacitance for X7S varies under the influence of electrical operating conditions such as voltage and frequency.

X7S dielectric chip usage covers the broad spectrum of industrial applications where known changes in capacitance due to applied voltages are acceptable.

### PART NUMBER (SEE PAGE 4 FOR COMPLETE PART NUMBER EXPLANATION)



### TYPICAL ELECTRICAL CHARACTERISTICS



# **X7S Dielectric**





Parame	ter/Test	X7S Specification Limits	Measuring Conditions				
Operating Tem	perature Range	-55°C to +125°C	Temperature Cycle Chamber				
Capac Dissipati	itance on Factor	Within specified tolerance ≤ 5.0% for ≥ 100V DC rating ≤ 5.0% for ≥ 25V DC rating ≤ 10.0% for ≥ 10V DC rating ≤ 10.0% for ≤ 10V DC rating Contact Factory for DF by PN	Freq.: 1.0 kHz ± 10% Voltage: 1.0Vrms ± .2V For Cap > 10 μF, 0.5Vrms @ 120Hz				
Insulation	Resistance	100,000ΜΩ or 1000ΜΩ - μF, whichever is less	Charge device with rated voltage for 120 ± 5 secs @ room temp/humidity				
Dielectric	: Strength	No breakdown or visual defects	Charge device with 250% of rated voltage for 1-5 seconds, w/charge and discharge current limited to 50 mA (max)				
	Appearance	No defects	Deflection: 2mm Test Time: 30 seconds 1mm/sec				
Resistance to	Capacitance Variation	≤ ±12%					
Flexure Stresses	Dissipation Factor	Meets Initial Values (As Above)					
	Insulation Resistance	≥ Initial Value x 0.3	90 mm				
Solder	rability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutectic for 5.0 ± 0.9				
	Appearance	No defects, <25% leaching of either end terminal					
	Capacitance Variation	≤ ±7.5%	B. J.				
Resistance to Solder Heat	Dissipation Factor	Meets Initial Values (As Above)	Dip device in eutectic solder at 260°C for 60 seconds. Store at room temperature for 24 ± 2 hours before measuring electrical properties.				
	Insulation Resistance	Meets Initial Values (As Above)					
	Dielectric Strength	Meets Initial Values (As Above)					
	Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes			
	Capacitance Variation	≤ ±7.5%	Step 2: Room Temp	≤ 3 minutes			
Thermal Shock	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +125°C ± 2°	30 ± 3 minutes			
	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes			
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles 24 ± 2 hours at ro				
	Appearance	No visual defects					
	Capacitance Variation	≤ ±12.5%	Charge device with 1.5 rated voltage (≤ 10V) in test chamber set at 125°C ± 2°C for 1000 hours (+48, -0)  Remove from test chamber and stabilize at room temperature for 24 ± 2 hours before measuring.				
Load Life	Dissipation Factor	≤ Initial Value x 2.0 (See Above)					
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)					
	Dielectric Strength	Meets Initial Values (As Above)	,				
	Appearance	No visual defects					
	Capacitance Variation	≤ ±12.5%	Store in a test chamber set at 85°C ± 2°C/ 85% ± 5% relative humidity for 1000 hours				
Load	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	(+48, -0) with rated voltage applied.				
Humidity	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from chamber and stabilize at room temperature and humidity for 24 ± 2 hours before measuring.				
	Dielectric Strength	Meets Initial Values (As Above)					

# **X7S Dielectric**





#### **PREFERRED SIZES ARE SHADED**

		<b>-</b>		<b>E</b>							
SIZE		0402		0603	0805	1206			1210		
Solder		Reflow/Wave		Reflow/Wave	Reflow/Wave	Reflow/Wave			Reflow Only		
Packag	ging	All Paper		All Paper	Paper/Embossed	Paper/Embossed			Paper/Embossed		
(L) Length	mm	1.00 ± 0.10		1.60 ± 0.15	2.01 ± 0.20	3.20 ± 0.20			3.20 ± 0.20		
(L) Length	(in.)	$(0.040 \pm 0.004)$		(0.063 ± 0.006)	(0.079 ± 0.008)		(0.126 ± 0.008)		(0.126 ± 0.008)		
W) Width	mm	0.50 ± 0.10		0.81 ± 0.15	1.25 ± 0.20	1.60 ± 0.20			2.50 ± 0.20		
	(in.)		± 0.004)	(0.032 ± 0.006)	(0.049 ± 0.008)		(0.063 ± 0.008)		(0.098 ± 0.008)		
(t)	mm		± 0.15	0.35 ± 0.15	0.50 ± 0.25		0.50 ± 0.25		0.50 ± 0.25		
Terminal	(in.)	(0.010 ± 0.006)		(0.014 ± 0.006)	(0.020 ± 0.010)	(0.020 ± 0.010)			(0.020 ± 0.010)		
_	WVDC	4	6.3	6.3	4	10	50	100	6.3		
Сар	100										
(pF)	150										
	220					ļ	-	-	- XW		
	330					L		/	VV		
	470							_	17		
	680					1		7)	DT. —		
	1000					- 0	_	11			
	1500 2200							$\smile$			
	3300					ł		1			
							1		l		
	4700					ŀ					
Com	6800										
Cap	0.010 0.015										
(μF)	0.015										
	0.022		С			_	_				
	0.033										
			С								
	0.068		C								
	0.10		C								
	0.15					ŀ					
-	0.22			G		-					
	0.33			G							
	0.47			G							
	1.0	Е		G		_	_				
	1.5	_		G .	N						
	2.2	Е			N N			Q			
<b>—</b>	3.3				N			٧_			
	4.7				N	Q					
	10					٧					
	22								Z		
	47								_		
	100										
	WVDC	4	6.3	6.3	4	10	50	100	6.3		
	SIZE	0402		0603	0805	1206			1210		
	VL										

[	Letter	Α	С	Е	G	J	K	М	N	Р	Q	Х	Υ	Z
	Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79
1	Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)
		PAPER				EMBOSSED								

<sup>\*</sup>Contact Factory for Specifications